

ABSTRACT

An apparatus is provided for scrubbing a substrate's edge. The apparatus comprises a stationary surface (i.e., a surface that does not rotate in a direction in which the substrate rotates) that is positioned so as to contact an edge (e.g., a circumferential edge, an edge portion of the substrate's major surface or a beveled surface of the substrate's edge) such that as the substrate rotates, a dragging force is generated between the stationary surface and the rotating substrate. In a preferred aspect the apparatus is adapted to support a substrate in a generally vertical orientation, and the stationary surface is positioned along a lower portion of the substrate's edge, such that fluid applied to the major surface of the substrate will flow onto, and thereby rinse, the stationary surface. Such a preferred configuration also may allow a substrate to be loaded and unloaded without needing to move the stationary surface. Preferably, when a substrate is loaded into the scrubbing apparatus, the substrate's edge will contact the stationary surface, and a separate step for positioning the stationary surface will not be needed.